#### 505133502 10/09/2018

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
DENING XU	09/18/2018
FENG OU	09/18/2018
QINGXIAO ZHENG	09/18/2018

### **RECEIVING PARTY DATA**

Name:	EMC IP HOLDING COMPANY LLC	
Street Address:	176 SOUTH STREET	
City:	HOPKINTON	
State/Country:	MASSACHUSETTS	
Postal Code:	01748	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16137211

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ATTORNEY DOCKET NUMBER:	206368.0428.6 (P267)	
NAME OF SUBMITTER:	ZI WANG	
SIGNATURE:	/Zi Wang/	
DATE SIGNED:	10/09/2018	

## **Total Attachments: 5**

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PATENT REEL: 047111 FRAME: 0379

#### ASSIGNMENT

WHEREAS, we, <u>Dening XU</u>, <u>Feng OU</u>, and <u>Oingxiao ZHENG</u>, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled PARTITION LEVEL RESTORE (Application), the specification of which:

[X]	[X] is being executed on even date herewith and is about to be filed in States Patent Office;		ne United	
[]	was filed on	as U.S. Application No	;	
[]	was patented under U.S. Patent 1	Noon	•	

WHEREAS, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the Commonwealth of Massachusetts and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the

giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

AND, we hereby authorize our attorneys, EMC IP Holding Company LLC, to insert here in parentheses (\_\_\_\_\_\_\_\_) the application number and filing date of said Application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date:	18/sep/18	Dania de La
	1 1	hyventor's Signature
Print fu	II name of first inventor:	Dening XU
Residence	e:	Unit# 2-2-2303,Longhu San Qian Cheng 218 Jian Ye Rd., Chenghua district Chengdu, Sichuan 610000, China
Citizensh	ip:	China
Mailing /	Address:	Same as above
Signed at	300 l; Gino Cii -17. changola ii.	(name) whose residential address is  Street · Chengled Hi-Tech Zone was personally was personally ment.  (signature of first witness)  Jed (location of witness signature)  of 2018. (date of signature)
known to	me, execute the above assign	(signature of second witness)
		i-Tech 20he (location of witness signature)
on this da	x 97/18	of 20/8 (date of signature)

Date: 18   507   18	Feng Ou
<del>, , , , , , , , , , , , , , , , , , , </del>	Inventor's Signature
Print full name of first inventor:	Feng OU
Residence:	XinHongJiYueCheng HuaYangJieDao HaiChangLu No.133 Tianfu New Area, Chengdu, Sichuan 610000, China
Citizenship:	China
Mailing Address:	Same as above
present and did see	(witness signature)
Gin. LIU (signature of Signed at C11-17, Chenzdu Hi-Ech Zone	g(location of witness signature)
on this day 0 / / of 20 / (date	e of signature)

Date: 18/50 108	Dive Xiao Zari Inventor's Signature
Print full name of first inventor:	Qingxino ZHENG
Residence:	#1601, Unit 3, Building 1, GuangHuaMeiLin (#855, YuYu Road) QingYang, Chengdu, Sichuan, 610071, China
Citizenship:	China
Mailing Address:	Same as above
Present and did see <u>Wing Xino Zhong</u> (known to me, execute the above assignment.  Baok: Guv (signature of Signed at CH-17, Chengolu Hi-Tech (location of on this day of 20 18. (dat	f witness signature)
i Ain Liu (name) who have the street the spresent and did see Then Ain Xiao (known to me, execute the above assignment.  Ain Liu (signature o	nose residential address is
Signed at C11-17 Chengdy Hi-Tech	ZARC (location of witness signature)
on this day 09/18 of 2018. (dat	